

5-146852-1 ✓ ACTIVE

AMPMODU | [AMPMODU Headers](#)

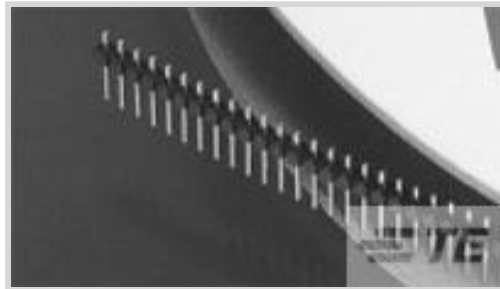
TE Internal #: 5-146852-1

PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm
[.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal,
AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **10**

Number of Rows: **1**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| PCB Connector Assembly Type | PCB Mount Header |
| Connector System | Board-to-Board |
| Header Type | Breakaway |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|----------------------------------|--------------|
| Connector Contact Load Condition | Fully Loaded |
| PCB Mount Orientation | Vertical |
| Number of Positions | 10 |
| Number of Rows | 1 |
| Board-to-Board Configuration | Parallel |

Body Features

| | |
|-----------------------|----------|
| Connector Profile | Standard |
| Primary Product Color | Black |

Contact Features

| | |
|------------------------------|-----------------|
| Mating Square Post Dimension | .64 mm[.025 in] |
| | 100 – 200 μin |
| Contact Shape & Form | Square |



| | |
|--|---|
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Tin-Lead |
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Tin |
| Contact Mating Area Plating Material Thickness | 2.54 – 5.08 μm [100 – 200 μin] |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3 A |

Termination Features

| | |
|---|-----------------------|
| Square Termination Post & Tail Dimension | .64 mm[.025 in] |
| Termination Post & Tail Length | 2.92 mm[.115 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |

Mechanical Attachment

| | |
|-------------------------|-------------|
| Mating Alignment | Without |
| PCB Mount Retention | Without |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |

Housing Features

| | |
|--------------------|----------------|
| Centerline (Pitch) | 2.54 mm[.1 in] |
| Housing Material | Thermoplastic |

Dimensions

| | |
|-----------------------------|-----------------|
| PCB Thickness (Recommended) | 1.6 mm[.063 in] |
|-----------------------------|-----------------|

Usage Conditions

| | |
|-----------------------------|--|
| Housing Temperature Rating | High |
| Operating Temperature Range | -65 – 105 $^{\circ}\text{C}$ [-85 – 221 $^{\circ}\text{F}$] |

Operation/Application

| | |
|------------------------|----------------|
| Solder Process Feature | Board Standoff |
| Circuit Application | Signal |

Industry Standards

| | |
|---|-----------------------|
| Compatible With Approved Standards Products | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |

Packaging Features

| | |
|--------------------|-------|
| Packaging Quantity | 25000 |
|--------------------|-------|



Packaging Type

Reel

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Pin-in-Paste capable to 260°C |

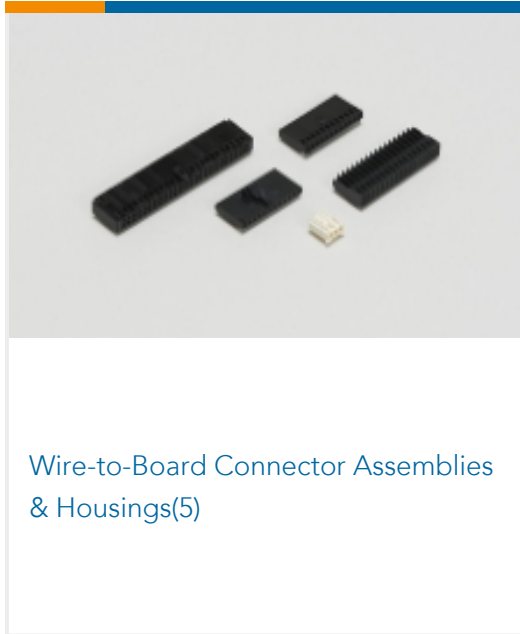
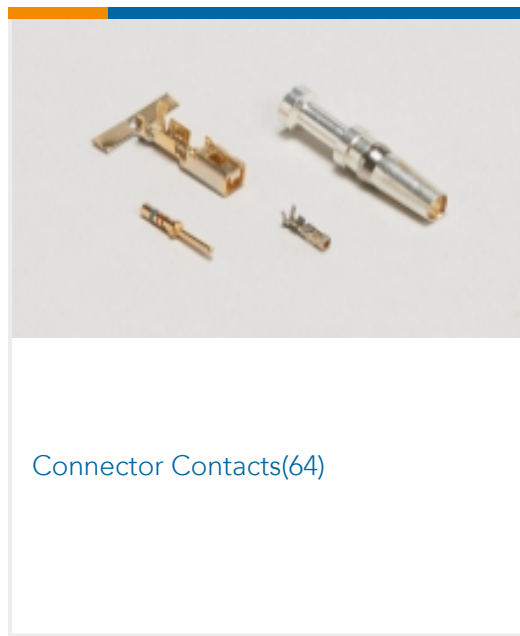
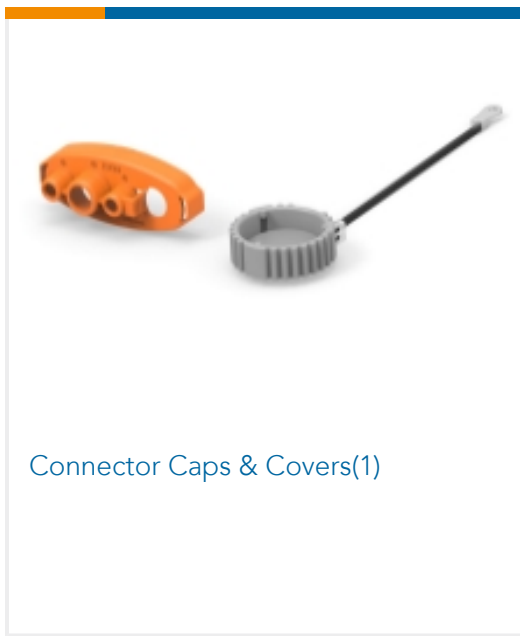
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | [AMPMODU Headers](#)



Customers Also Bought



Documents

Product Drawings

[B/A REELED SRST HDR ASSY, SN](#)

English

Datasheets & Catalog Pages

[AMPMODU_INTERCONNECTION_SYSTEM_SECTION5](#)

English

[1-1773720-9_AMPMODU_MOD_IV_V_ORG](#)



English